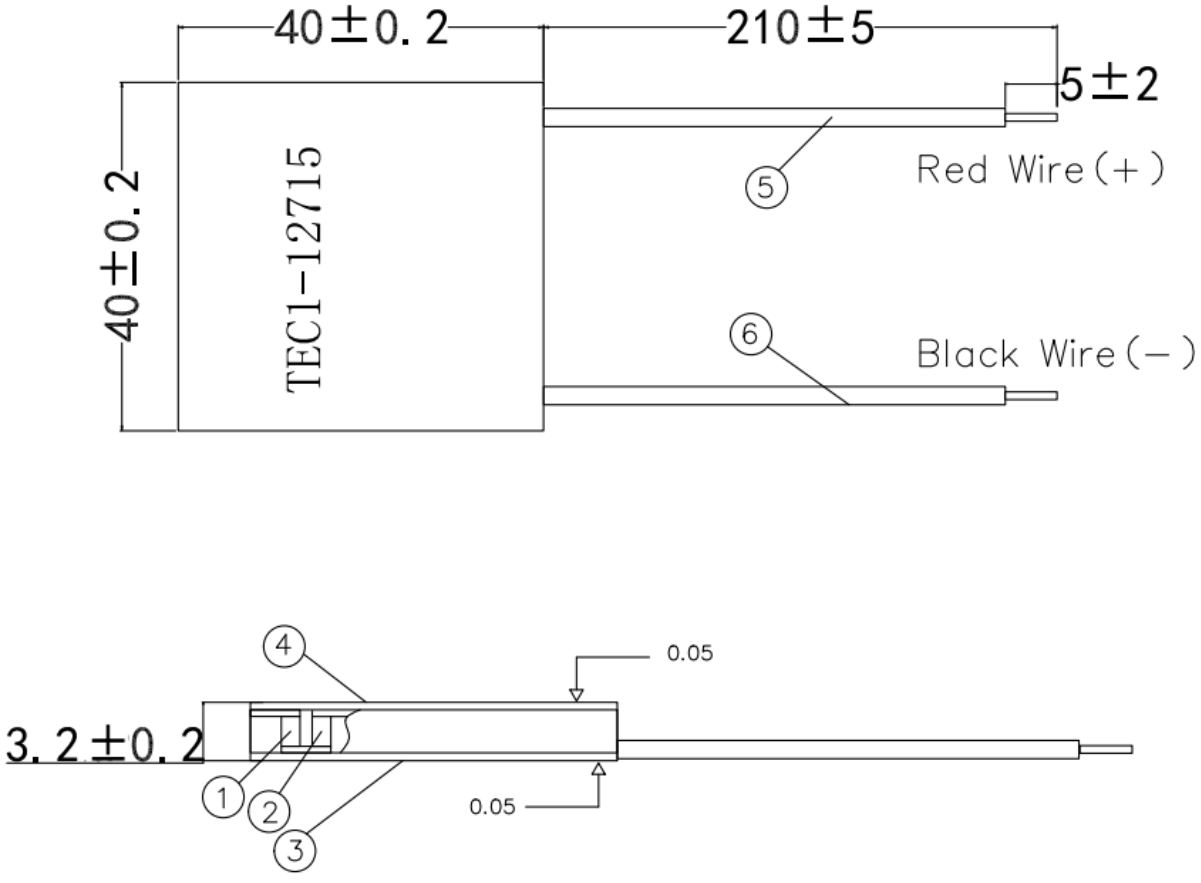
Huahai Technology

TEC1-12715

Performance parameter：

item	value	Test condition
最大电流 Imax（A）	15	Qc=0,DT=Dtmax,Th=31℃
最大电压 Vmax（V）	15.8	Qc=0,DT=Dtmax,Th=31℃
最大吸热量 Qcmax（W）	130	I=Imax,Dt=0,Th=31℃
最大温差 DTmax	65℃	Qc=0 I=Imax, Th=31℃
电阻 R（Ω）	0.7-0.9	Ta=25℃

Product drawing



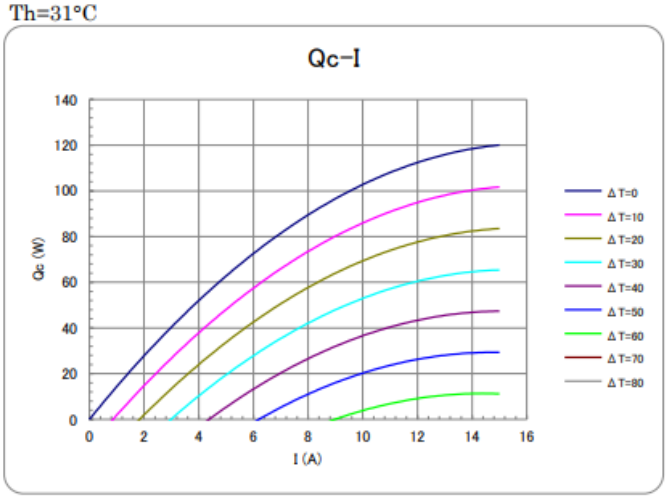
Other parameters

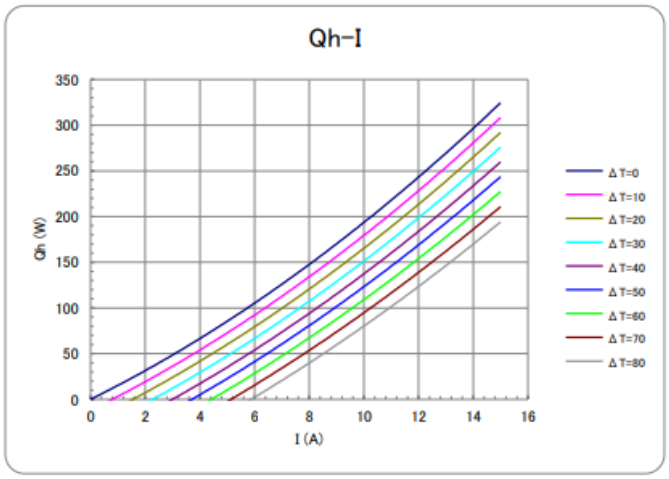
1. The number of product particles is 127 pairs; The melting point of solder is 138°C.
2. Wire: UL3132#20 silicone wire, temperature resistance 150°C; Meet REAC H and ROHS environmental requirements. Wire ends on tin.
3. Hot and cold surface: red line through the positive electrode, printing positi on for the cold surface.

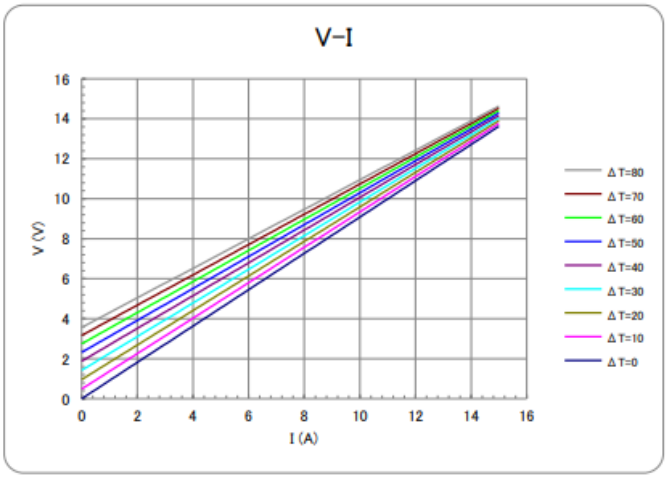
4. Sealing adhesive: RTV adhesive.
5. Recommended operating temperature range: -40~65℃.
6. The tensile strength standard of wire welding is: static parallel tension 2Kg, keep for 1 minute, no bad phenomenon such as broken wire.
7. The resistance test adopts AC high-frequency milliohm meter or handheld LCR digital bridge (TH2822 series), and the resistance value cannot be tested with a multimeter. Resistance Resistance value will change with the change of temperature, the ambient temperature increases or decreases by 1 ℃, the resistance value increases or decreases by 5 ‰.
8. The cold and hot exchange should wait for the temperature of the hot and cold surface to return to room temperature (generally recommended for more than 15 minutes), otherwise it is easy to cause damage to the semiconductor cooler.

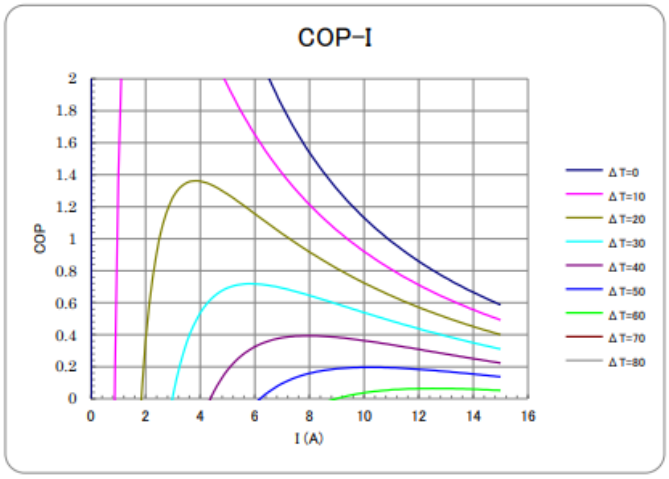
Performance graph

Th=31°C









Th: Temperature of heat radiating side
Qc: Heat absorbed (pumped)
I: Input current
ΔT: Temperature difference between heat radiating side and heat absorbing side

V: Input voltage
Qh: Heat radiated
COP: Coefficient of performance
In air